

Appl. No. 10/033,663
Amdt. Dated Mar. 1, 2004
Reply to Office Action of Nov. 28, 2003

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A modular jack mounted on a mother board, comprising:

an insulative housing defining a receiving space;

a terminal module received in the receiving space and comprising a plurality of terminals, each terminal comprising a mounting portion, an inclined contacting portion extending from a front end of the mounting portion and a tail portion extending rearwardly from a rear end of the mounting portion; and

an electronic component assembled in the insulative housing to eliminate noise and comprising a plurality of upper contacts for electrically connecting with ~~the tail portions of~~ the terminals, and a plurality of lower contacts for connecting with the mother board, each of the upper contacts of the electronic component comprising a fork-shaped mating portion defining a receiving groove for snugly receiving corresponding tail portion of the terminal.

Claims 2 (currently amended): The modular jack as described in claim 1, ~~wherein each of the upper contacts of the electronic component comprises a fork-shaped mating portion defining a receiving groove for receiving corresponding tail portion of the terminal~~ the terminal module includes a pair of opposite printed circuit boards, and wherein the mounting portions of the terminals

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are sandwiched between the opposite printed circuit boards.

Claim 3 (canceled)

Claim 4 (original): The modular jack as described in claim 1, wherein the electronic component comprises a main base for retaining the upper and lower contacts, a plurality of middle contacts mounted on the main base, a filter printed circuit board assembled on the main base for connecting with the lower contacts and the middle contacts and a magnetic coil assembled on the main base for connecting with the upper contacts, the middle contacts and the lower contacts.

Claim 5 (currently amended): A modular jack assembly comprising:
an insulative housing defining upper and lower receiving spaces and a rear receiving space therein;

upper and lower terminal modules respectively disposed in the corresponding upper and lower receiving spaces with a plurality of contacts thereof;

a pair of discrete front and rear electronic components retainably spatially located in said rear space, each of said pair of front and rear electronic components including a base with a filter printed circuit board and magnetic coil, a plurality of upper contacts located on an upper portion of the base and engaged with the corresponding contacts, respectively, and a plurality of lower contacts located on a lower portion of the base and extending downwardly beyond a bottom face of the assembly to assemble to a main printed circuit board on which the assembly is seated.

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Claim 6 (new): The modular jack assembly as described in claim 5, wherein each of the upper and lower contacts of the electronic component comprises a fork-shaped mating portion defining a receiving groove for receiving a corresponding contact of the upper and lower terminal modules.

Claim 7 (new): The modular jack assembly as described in claim 5, wherein each contact of the upper and lower terminal modules has a fork-shaped tail portion defining a receiving groove for snugly receiving a corresponding contact of the electronic component.

Claim 8 (new): The modular jack assembly as described in claim 5, wherein the electronic component comprises a main base for retaining the upper and lower contacts, a plurality of middle contacts mounted on the main base, a filter printed circuit board assembled on the main base for connecting with the lower contacts and the middle contacts and a magnetic coil assembled on the main base for connecting with the upper contacts, the middle contacts and the lower contacts.

Claim 9 (new): The modular jack assembly as described in claim 5, wherein each contact of the upper terminal modules has a tail portion, and wherein the tail portion of the upper terminal module is longer than the tail portion of the lower terminal module.

Claim 10 (new) The modular jack assembly as described in claim 5, wherein the front electronic component is connected to the upper terminal module while the rear electronic component is connected to the lower terminal module, respectively.

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Claim 11 (new): A modular jack mounted on a mother board, comprising:
an insulative housing defining a receiving space;
a terminal module received in the receiving space and comprising a plurality of terminals, each terminal comprising a mounting portion, an inclined contacting portion extending from a front end of the mounting portion and a tail portion extending rearwardly from a rear end of the mounting portion, the tail portion of each terminal being substantially fork-shaped and defining a receiving groove;
and
an electronic component assembled in the insulative housing to eliminate noise and comprising a plurality of upper contacts snugly receiving in corresponding receiving grooves of the tail portions of the terminals, and a plurality of lower contacts for connecting with the mother board.

Claim 12 (new): The modular jack as described in claim 10, wherein the electronic component comprises a main base for retaining the upper and lower contacts, a plurality of middle contacts mounted on the main base, a filter printed circuit board assembled on the main base for connecting with the lower contacts and the middle contacts and a magnetic coil assembled on the main base for connecting with the upper contacts, the middle contacts and the lower contacts.